What is claimed is:

1. A solder powder-cleaning agent comprising:

at least one of components selected from a group consisting of N-methylpyrrolidone, 2-pyrrolidone, dimethylsulfoxide, propylene carbonate, sulfolane, and γ-butyrolactone.

2. The solder powder-cleaning agent according to Claim 1, further comprising:

at least one of a stabilizing agent and an additive.

3. A method for making solder powder comprising:

a powder-forming step in which the solder powder is formed in liquid; and

a cleaning step in which the solder powder obtained from the powder-forming step is cleaned using the solder powder-cleaning agent according to Claim 1 or 2.

4. The method for making solder powder according to Claim 3,

wherein, in the cleaning step, a stir cleaning process in which a cleaning liquid including the solder powder-cleaning agent is stirred at 100 to 500 rpm for 5 to 10 minutes and a supernatant liquid-removing process in which the supernatant liquid formed by the mixture being allowed to stand after the stir cleaning process is removed are repeated several times and then, the remaining slurry is immersed in rinsing cleaning liquid, and after the supernatant liquid formed by the mixture being allowed to stand is removed, the resultant is dried and becomes solder powder.

5. The method for making solder powder according to Claim 3,

wherein, in the cleaning step, an ultrasonic cleaning process in which ultrasonic waves of 25 to 40 kHz and 300 to 600 W are applied to a cleaning liquid including the solder powder-cleaning agent for 5 to 10 minutes and a supernatant liquid-removing process in which the supernatant liquid formed by the mixture being allowed to stand after the ultrasonic cleaning process is removed are repeated several times and then, the remaining slurry is immersed in rinsing cleaning liquid, and after the supernatant liquid formed by the mixture being allowed to stand is removed, the resultant is dried and becomes solder powder.

6. The method for making solder powder according to Claim 3,

wherein, in the cleaning step, a process in which an ultrasonic cleaning process in which ultrasonic waves of 25 to 40 kHz and 300 to 600 W are applied to a cleaning liquid for 5 to 10 minutes and a stir cleaning process in which a cleaning liquid including the solder powder-cleaning agent is stirred at 100 to 500 rpm for 5 to 10 minutes are performed either consecutively in a certain order or simultaneously, and a supernatant liquid-removing process in which the supernatant liquid formed by the mixture being allowed to stand after the processes is removed is repeated several times and then, the remaining slurry is immersed in rinsing cleaning liquid, and after the supernatant liquid formed by the mixture being allowed to stand is removed, the resultant is dried and becomes solder powder.

What is claimed is:

1. A solder powder-cleaning agent comprising:

at least one of components selected from a group consisting of N-methylpyrrolidone, 2-pyrrolidone, dimethylsulfoxide, propylene carbonate, sulfolane, and γ-butyrolactone.

2. The solder powder-cleaning agent according to Claim 1, further comprising:

at least one of a stabilizing agent and an additive.

3. The solder powder-cleaning agent according to Claim 1 or 2, wherein the solder powder-cleaning agent includes 85 to 100 mass% of the components.

4. The solder powder-cleaning agent according to any one of Claims 1 to 3, wherein the solder powder-cleaning agent includes 0.1 to 15 mass% of the stabilizing agent and the additive.

5. A method for making solder powder comprising:

a powder-forming step in which the solder powder is formed in liquid; and

a cleaning step in which the solder powder obtained from the powder-forming step is cleaned using the solder powder-cleaning agent according to any one of Claim 1 to 4.

6. The method for making solder powder according to Claim 5,

wherein, in the cleaning step, a stir cleaning process in which a cleaning liquid including the solder powder-cleaning agent is stirred at 100 to 500 rpm for 5 to 10 minutes and a supernatant liquid-removing process in which the supernatant liquid formed by the mixture being allowed to stand after the stir cleaning process is removed are repeated several times and then, the remaining slurry is immersed in rinsing cleaning liquid, and after the supernatant liquid formed by the mixture being allowed to stand is removed, the resultant is dried and becomes solder powder.

7. The method for making solder powder according to Claim 5,

wherein, in the cleaning step, an ultrasonic cleaning process in which ultrasonic waves of 25 to 40 kHz and 300 to 600 W are applied to a cleaning liquid including the solder

powder-cleaning agent for 5 to 10 minutes and a supernatant liquid-removing process in which the supernatant liquid formed by the mixture being allowed to stand after the ultrasonic cleaning process is removed are repeated several times and then, the remaining slurry is immersed in rinsing cleaning liquid, and after the supernatant liquid formed by the mixture being allowed to stand is removed, the resultant is dried and becomes solder powder.

8. The method for making solder powder according to Claim 5,

wherein, in the cleaning step, a process in which an ultrasonic cleaning process in which ultrasonic waves of 25 to 40 kHz and 300 to 600 W are applied to a cleaning liquid for 5 to 10 minutes and a stir cleaning process in which a cleaning liquid including the solder powder-cleaning agent is stirred at 100 to 500 rpm for 5 to 10 minutes are performed either consecutively in a certain order or simultaneously, and a supernatant liquid-removing process in which the supernatant liquid formed by the mixture being allowed to stand after the processes is removed is repeated several times and then, the remaining slurry is immersed in rinsing cleaning liquid, and after the supernatant liquid formed by the mixture being allowed to stand is removed, the resultant is dried and becomes solder powder.